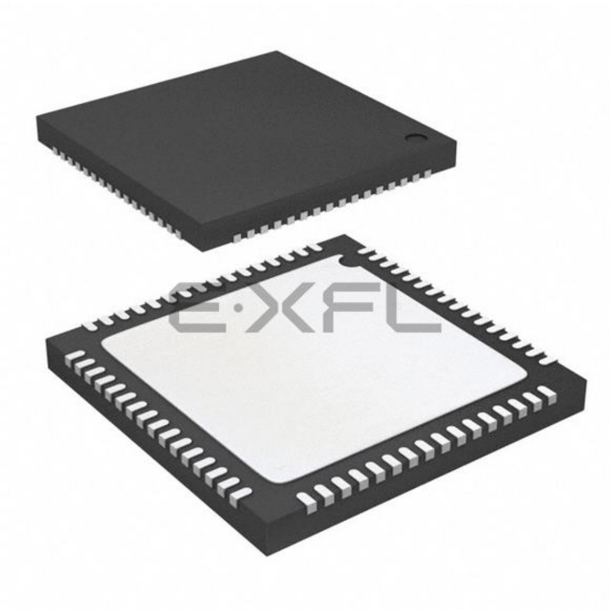
Analog Devices Inc. - ADUC7024BCPZ62 Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	44MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	PLA, PWM, PSM, Temp Sensor, WDT
Number of I/O	30
Program Memory Size	62KB (31K x16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 32
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 10x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad, CSP
Supplier Device Package	64-LFCSP-VQ (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/aduc7024bcpz62

Table 4. I²C Timing in Fast Mode (400 kHz)

		Slave		Master	
Parameter	Description	Min	Max	Typ	Unit
t_L	SCL low pulse width[1]	200		1360	ns
t_H	SCL high pulse width[1]	100		1140	ns
t_{SHD}	Start condition hold time	300			ns
t_{DSU}	Data setup time	100		740	ns
t_{DHD}	Data hold time	0		400	ns
t_{RSU}	Setup time for repeated start	100			ns
t_{PSU}	Stop condition setup time	100		400	ns
t_{BUF}	Bus-free time between a stop condition and a start condition	1.3			µs
t_R	Rise time for both SCL and SDA		300	200	ns
t_F	Fall time for both SCL and SDA		300		ns
t_{SUP}	Pulse width of spike suppressed		50		ns

[1] t_{HCLK} depends on the clock divider or CD bits in the POWCON MMR. $t_{HCLK} = t_{UCLK}/2^{CD}$; see Figure 67.

Table 5. I²C Timing in Standard Mode (100 kHz)

		Slave		Master	
Parameter	Description	Min	Max	Typ	Unit
t_L	SCL low pulse width[1]	4.7			µs
t_H	SCL high pulse width[1]	4.0			ns
t_{SHD}	Start condition hold time	4.0			µs
t_{DSU}	Data setup time	250			ns
t_{DHD}	Data hold time	0	3.45		µs
t_{RSU}	Setup time for repeated start	4.7			µs
t_{PSU}	Stop condition setup time	4.0			µs
t_{BUF}	Bus-free time between a stop condition and a start condition	4.7			µs
t_R	Rise time for both SCL and SDA		1		µs
t_F	Fall time for both SCL and SDA		300		ns

[1] t_{HCLK} depends on the clock divider or CD bits in the POWCON MMR. $t_{HCLK} = t_{UCLK}/2^{CD}$; see Figure 67.

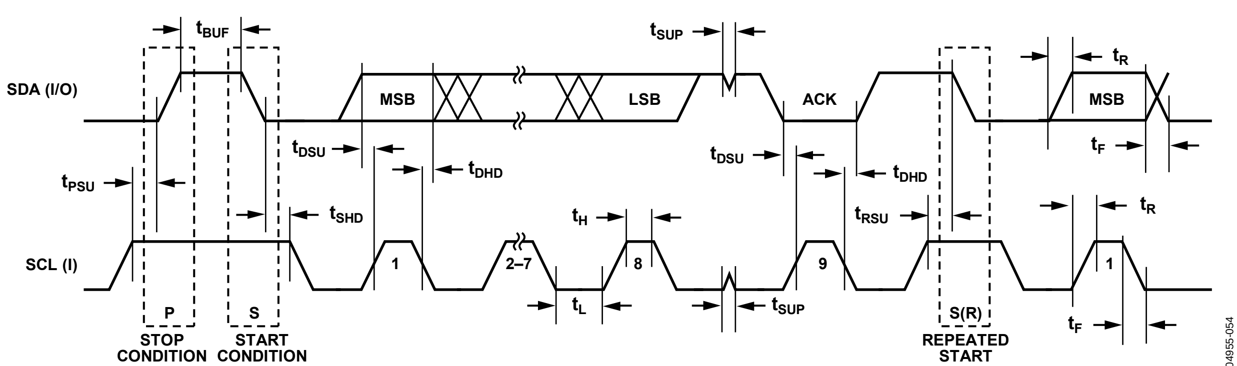


Figure 14. I²C Compatible Interface Timing

Table 6. SPI Master Mode Timing (Phase Mode = 1)

Parameter	Description	Min	Typ	Max	Unit
t_{SL}	SCLK low pulse width[1]		(SPIDIV + 1) × t_{HCLK}		ns
t_{SH}	SCLK high pulse width[1]		(SPIDIV + 1) × t_{HCLK}		ns
t_{DAV}	Data output valid after SCLK edge			25	ns
t_{DSU}	Data input setup time before SCLK edge[2]	1 × t_{UCLK}			ns
t_{DHD}	Data input hold time after SCLK edge[2]	2 × t_{UCLK}			ns
t_{DF}	Data output fall time		5	12.5	ns
t_{DR}	Data output rise time		5	12.5	ns
t_{SR}	SCLK rise time		5	12.5	ns
t_{SF}	SCLK fall time		5	12.5	ns

[1] t_{HCLK} depends on the clock divider or CD bits in the POWCONMMR. $t_{HCLK} = t_{UCLK}/2^{CD}$; see Figure 67.
[2] t_{UCLK} = 23.9 ns. It corresponds to the 41.78 MHz internal clock from the PLL before the clock divider; see Figure 67.

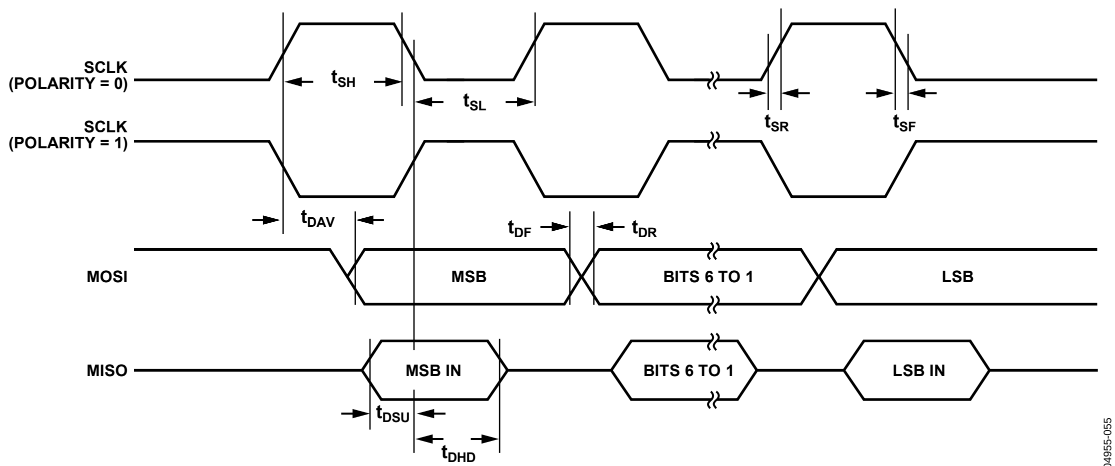


Figure 15. SPI Master Mode Timing (Phase Mode = 1)

ABSOLUTE MAXIMUM RATINGS

AGND = REFGND = DACGND = GND_{REF}, T_A = 25°C, unless otherwise noted.

Table 10.

Parameter	Rating
AV_{DD} to IOV_{DD}	−0.3 V to +0.3 V
AGND to DGND	−0.3 V to +0.3 V
IOV_{DD} to IOGND, AV_{DD} to AGND	−0.3 V to +6 V
Digital Input Voltage to IOGND	−0.3 V to +5.3 V
Digital Output Voltage to IOGND	−0.3 V to IOV_{DD} + 0.3 V
V_{REF} to AGND	−0.3 V to AV_{DD} + 0.3 V
Analog Inputs to AGND	−0.3 V to AV_{DD} + 0.3 V
Analog Outputs to AGND	−0.3 V to AV_{DD} + 0.3 V
Operating Temperature Range, Industrial	−40°C to +125°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
θ_{JA} Thermal Impedance	
40-Lead LFCSP	26°C/W
49-Ball CSP_BGA	80°C/W
64-Lead LFCSP	24°C/W
64-Ball CSP_BGA	75°C/W
64-Lead LQFP	47°C/W
80-Lead LQFP	38°C/W
Peak Solder Reflow Temperature	
SnPb Assemblies (10 sec to 30 sec)	240°C
RoHS Compliant Assemblies (20 sec to 40 sec)	260°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

Only one absolute maximum rating can be applied at any one time.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

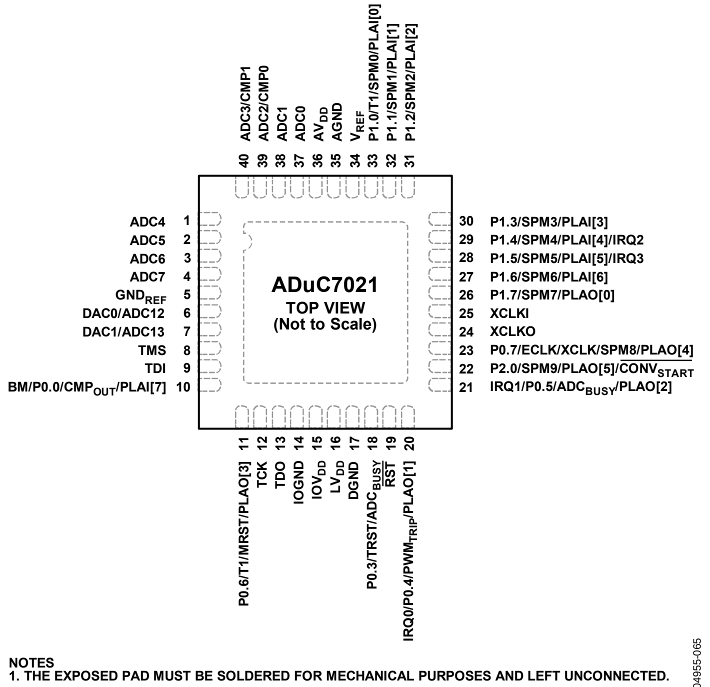


Figure 21. 40-Lead LFCSP_WQ Pin Configuration (ADuC7021)

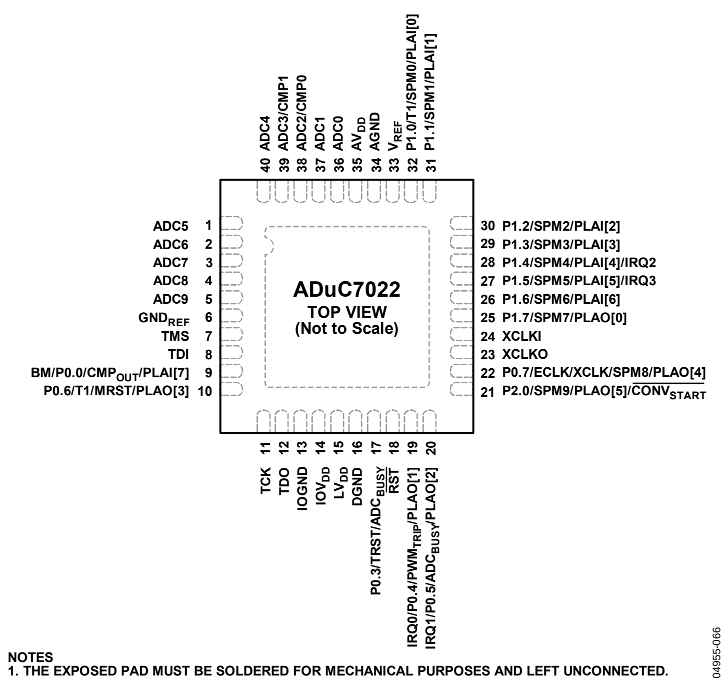


Figure 22. 40-Lead LFCSP_WQ Pin Configuration (ADuC7022)

Table 12. Pin Function Descriptions (ADuC7024/ADuC7025 64-Lead LFCSP_VQ and 64-Lead LQFP)

Pin No.	Mnemonic	Description
1	ADC4	Single-Ended or Differential Analog Input 4.
2	ADC5	Single-Ended or Differential Analog Input 5.
3	ADC6	Single-Ended or Differential Analog Input 6.
4	ADC7	Single-Ended or Differential Analog Input 7.
5	ADC8	Single-Ended or Differential Analog Input 8.
6	ADC9	Single-Ended or Differential Analog Input 9.
7	GND_{REF}	Ground Voltage Reference for the ADC. For optimal performance, the analog power supply should be separated from IOGND and DGND.
8	ADCNEG	Bias Point or Negative Analog Input of the ADC in Pseudo Differential Mode. Must be connected to the ground of the signal to convert. This bias point must be between 0 V and 1 V.
9	DAC0/ADC12	DAC0 Voltage Output/Single-Ended or Differential Analog Input 12. DAC outputs are not present on the ADuC7025.
10	DAC1/ADC13	DAC1 Voltage Output/Single-Ended or Differential Analog Input 13. DAC outputs are not present on the ADuC7025.
11	TMS	JTAG Test Port Input, Test Mode Select. Debug and download access.
12	TDI	JTAG Test Port Input, Test Data In. Debug and download access
13	P4.6/PLAO[14]	General-Purpose Input and Output Port 4.6/Programmable Logic Array Output Element 14.
14	P4.7/PLAO[15]	General-Purpose Input and Output Port 4.7/Programmable Logic Array Output Element 15.
15	BM/P0.0/CMP_{OUT}/PLAI[7]	Multifunction I/O Pin. Boot mode. The ADuC7024/ADuC7025 enter download mode if BM is low at reset and execute code if BM is pulled high at reset through a 1 kΩ resistor/General-Purpose Input and Output Port 0.0/Voltage Comparator Output/Programmable Logic Array Input Element 7.
16	P0.6/T1/MRST/PLAO[3]	Multifunction Pin, Driven Low After Reset. General-Purpose Output Port 0.6/Timer1 Input/Power-On Reset Output/Programmable Logic Array Output Element 3.
17	TCK	JTAG Test Port Input, Test Clock. Debug and download access.
18	TDO	JTAG Test Port Output, Test Data Out. Debug and download access.
19	IOGND	Ground for GPIO (see Table 78). Typically connected to DGND.
20	IOV_{DD}	3.3 V Supply for GPIO (see Table 78) and Input of the On-Chip Voltage Regulator.
21	LV_{DD}	2.6 V Output of the On-Chip Voltage Regulator. This output must be connected to a 0.47 µF capacitor to DGND only.
22	DGND	Ground for Core Logic.
23	P3.0/$PWM0_H$/PLAI[8]	General-Purpose Input and Output Port 3.0/PWM Phase 0 High-Side Output/Programmable Logic Array Input Element 8.
24	P3.1/$PWM0_L$/PLAI[9]	General-Purpose Input and Output Port 3.1/PWM Phase 0 Low-Side Output/Programmable Logic Array Input Element 9.
25	P3.2/$PWM1_H$/PLAI[10]	General-Purpose Input and Output Port 3.2/PWM Phase 1 High-Side Output/Programmable Logic Array Input Element 10.
26	P3.3/$PWM1_L$/PLAI[11]	General-Purpose Input and Output Port 3.3/PWM Phase 1 Low-Side Output/Programmable Logic Array Input Element 11.
27	P0.3/TRST/ADC_{BUSY}	General-Purpose Input and Output Port 0.3/JTAG Test Port Input, Test Reset/ADC_{BUSY} Signal Output.
28	$\overline{RST}$	Reset Input, Active Low.
29	P3.4/$PWM2_H$/PLAI[12]	General-Purpose Input and Output Port 3.4/PWM Phase 2 High-Side Output/Programmable Logic Array Input 12.
30	P3.5/$PWM2_L$/PLAI[13]	General-Purpose Input and Output Port 3.5/PWM Phase 2 Low-Side Output/Programmable Logic Array Input Element 13.
31	IRQ0/P0.4/PWM_{TRIP}/PLAO[1]	Multifunction I/O Pin. External Interrupt Request 0, Active High/General-Purpose Input and Output Port 0.4/PWM Trip External Input/Programmable Logic Array Output Element 1.
32	IRQ1/P0.5/ADC_{BUSY}/PLAO[2]	Multifunction I/O Pin. External Interrupt Request 1, Active High/General-Purpose Input and Output Port 0.5/ADC_{BUSY} Signal Output/Programmable Logic Array Output Element 2.
33	P2.0/SPM9/PLAO[5]/$\overline{CONV_{START}}$	Serial Port Multiplexed. General-Purpose Input and Output Port 2.0/UART/Programmable Logic Array Output Element 5/Start Conversion Input Signal for ADC.
34	P0.7/ECLK/XCLK/SPM8/PLAO[4]	Serial Port Multiplexed. General-Purpose Input and Output Port 0.7/Output for External Clock Signal/Input to the Internal Clock Generator Circuits/UART/Programmable Logic Array Output Element 4.
35	XCLKO	Output from the Crystal Oscillator Inverter.
36	XCLKI	Input to the Crystal Oscillator Inverter and Input to the Internal Clock Generator Circuits.

Pin No.	Mnemonic	Description
37	P3.6/PWM_{TRIP}/PLAI[14]	General-Purpose Input and Output Port 3.6/PWM Safety Cutoff/Programmable Logic Array Input Element 14.
38	P3.7/PWM_{SYNC}/PLAI[15]	General-Purpose Input and Output Port 3.7/PWM Synchronization Input and Output/ Programmable Logic Array Input Element 15.
39	P1.7/SPM7/PLAO[0]	Serial Port Multiplexed. General-Purpose Input and Output Port 1.7/UART, SPI/Programmable Logic Array Output Element 0.
40	P1.6/SPM6/PLAI[6]	Serial Port Multiplexed. General-Purpose Input and Output Port 1.6/UART, SPI/Programmable Logic Array Input Element 6.
41	IOGND	Ground for GPIO (see Table 78). Typically connected to DGND.
42	IOV_{DD}	3.3 V Supply for GPIO (see Table 78) and Input of the On-Chip Voltage Regulator.
43	P4.0/PLAO[8]	General-Purpose Input and Output Port 4.0/Programmable Logic Array Output Element 8.
44	P4.1/PLAO[9]	General-Purpose Input and Output Port 4.1/Programmable Logic Array Output Element 9.
45	P1.5/SPM5/PLAI[5]/IRQ3	Serial Port Multiplexed. General-Purpose Input and Output Port 1.5/UART, SPI/Programmable Logic Array Input Element 5/External Interrupt Request 3, Active High.
46	P1.4/SPM4/PLAI[4]/IRQ2	Serial Port Multiplexed. General-Purpose Input and Output Port 1.4/UART, SPI/Programmable Logic Array Input Element 4/External Interrupt Request 2, Active High.
47	P1.3/SPM3/PLAI[3]	Serial Port Multiplexed. General-Purpose Input and Output Port 1.3/UART, I2C1/Programmable Logic Array Input Element 3.
48	P1.2/SPM2/PLAI[2]	Serial Port Multiplexed. General-Purpose Input and Output Port 1.2/UART, I2C1/Programmable Logic Array Input Element 2.
49	P1.1/SPM1/PLAI[1]	Serial Port Multiplexed. General-Purpose Input and Output Port 1.1/UART, I2C0/Programmable Logic Array Input Element 1.
50	P1.0/T1/SPM0/PLAI[0]	Serial Port Multiplexed. General-Purpose Input and Output Port 1.0/Timer1 Input/UART, I2C0/ Programmable Logic Array Input Element 0.
51	P4.2/PLAO[10]	General-Purpose Input and Output Port 4.2/Programmable Logic Array Output Element 10.
52	P4.3/PLAO[11]	General-Purpose Input and Output Port 4.3/Programmable Logic Array Output Element 11.
53	P4.4/PLAO[12]	General-Purpose Input and Output Port 4.4/Programmable Logic Array Output Element 12.
54	P4.5/PLAO[13]	General-Purpose Input and Output Port 4.5/Programmable Logic Array Output Element 13.
55	V_{REF}	2.5 V Internal Voltage Reference. Must be connected to a 0.47 μF capacitor when using the internal reference.
56	DAC_{REF}	External Voltage Reference for the DACs. Range: DACGND to $DACV_{DD}$.
57	DACGND	Ground for the DAC. Typically connected to AGND.
58	AGND	Analog Ground. Ground reference point for the analog circuitry.
59	AV_{DD}	3.3 V Analog Power.
60	$DACV_{DD}$	3.3 V Power Supply for the DACs. Must be connected to AV_{DD}.
61	ADC0	Single-Ended or Differential Analog Input 0.
62	ADC1	Single-Ended or Differential Analog Input 1.
63	ADC2/CMP0	Single-Ended or Differential Analog Input 2/Comparator Positive Input.
64	ADC3/CMP1	Single-Ended or Differential Analog Input 3/Comparator Negative Input.
0	EP	Exposed Pad. The pin configuration for the ADuC7024/ADuC7025 LFCSP_VQ has an exposed pad that must be soldered for mechanical purposes and left unconnected.

ADuC7026/ADuC7027

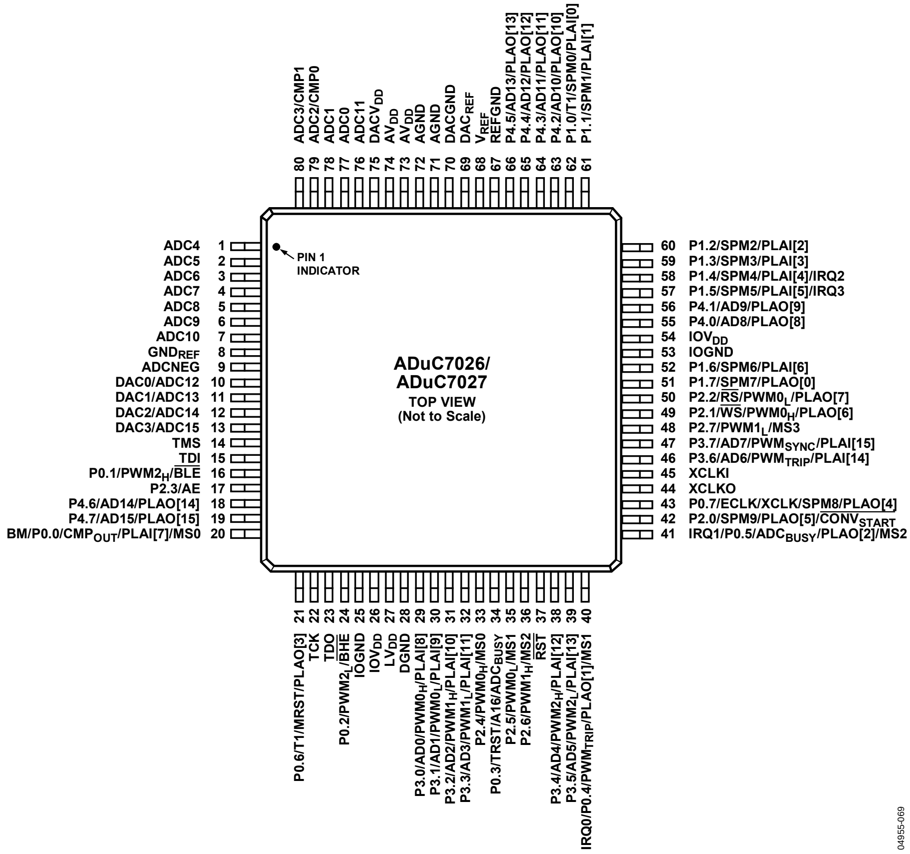


Figure 25. 80-Lead LQFP Pin Configuration (ADuC7026/ADuC7027)

Table 13. Pin Function Descriptions (ADuC7026/ADuC7027)

Pin No.	Mnemonic	Description
1	ADC4	Single-Ended or Differential Analog Input 4.
2	ADC5	Single-Ended or Differential Analog Input 5.
3	ADC6	Single-Ended or Differential Analog Input 6.
4	ADC7	Single-Ended or Differential Analog Input 7.
5	ADC8	Single-Ended or Differential Analog Input 8.
6	ADC9	Single-Ended or Differential Analog Input 9.
7	ADC10	Single-Ended or Differential Analog Input 10.
8	GND_{REF}	Ground Voltage Reference for the ADC. For optimal performance, the analog power supply should be separated from IOGND and DGND.
9	ADCNEG	Bias Point or Negative Analog Input of the ADC in Pseudo Differential Mode. Must be connected to the ground of the signal to convert. This bias point must be between 0 V and 1 V.
10	DAC0/ADC12	DAC0 Voltage Output/Single-Ended or Differential Analog Input 12. DAC outputs are not present on the ADuC7027.
11	DAC1/ADC13	DAC1 Voltage Output/Single-Ended or Differential Analog Input 13. DAC outputs are not present on the ADuC7027.
12	DAC2/ADC14	DAC2 Voltage Output/Single-Ended or Differential Analog Input 14. DAC outputs are not present on the ADuC7027.
13	DAC3/ADC15	DAC3 Voltage Output/Single-Ended or Differential Analog Input 15. DAC outputs are not present on the ADuC7027.
14	TMS	JTAG Test Port Input, Test Mode Select. Debug and download access.
15	TDI	JTAG Test Port Input, Test Data In. Debug and download access.
16	P0.1/PWM2$_H$/$\overline{BLE}$	General-Purpose Input and Output Port 0.1/PWM Phase 2 High-Side Output/External Memory Byte Low Enable.
17	P2.3/AE	General-Purpose Input and Output Port 2.3/External Memory Access Enable.

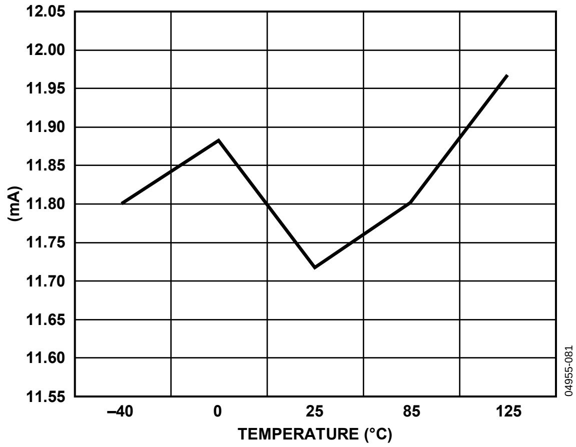


Figure 40. Current Consumption vs. Temperature @ CD = 3

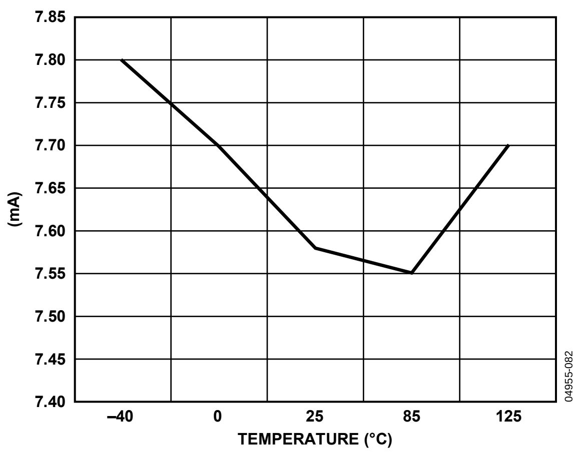


Figure 41. Current Consumption vs. Temperature @ CD = 7

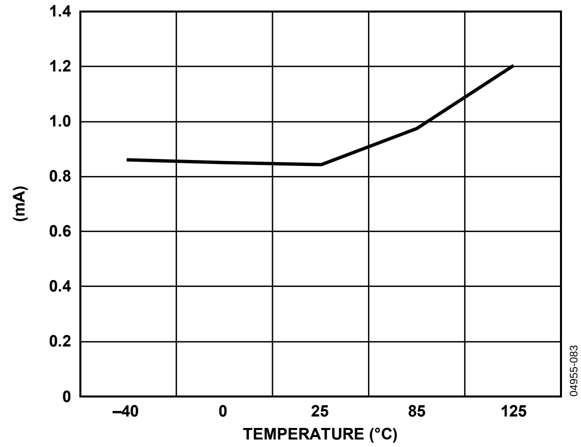


Figure 42. Current Consumption vs. Temperature in Sleep Mode

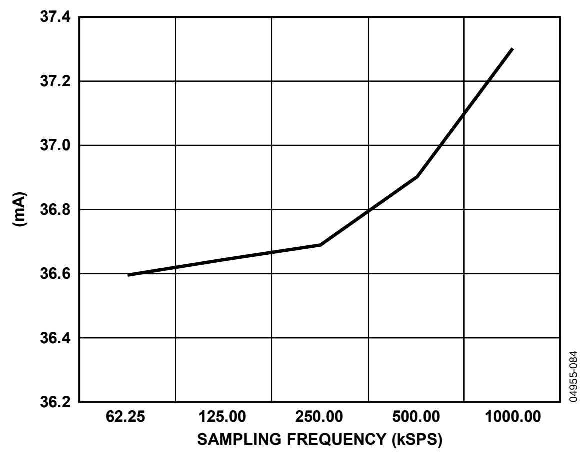


Figure 43. Current Consumption vs. Sampling Frequency

OVERVIEW OF THE ARM7TDMI CORE

The ARM7® core is a 32-bit reduced instruction set computer (RISC). It uses a single 32-bit bus for instruction and data. The length of the data can be eight bits, 16 bits, or 32 bits. The length of the instruction word is 32 bits.

The ARM7TDMI is an ARM7 core with four additional features.

- T support for the thumb (16-bit) instruction set.
- D support for debug.
- M support for long multiplications.
- I includes the EmbeddedICE module to support embedded system debugging.

THUMB MODE (T)

An ARM instruction is 32 bits long. The ARM7TDMI processor supports a second instruction set that is compressed into 16 bits, called the thumb instruction set. Faster execution from 16-bit memory and greater code density can usually be achieved by using the thumb instruction set instead of the ARM instruction set, which makes the ARM7TDMI core particularly suitable for embedded applications.

However, the thumb mode has two limitations.

- Thumb code typically requires more instructions for the same job. As a result, ARM code is usually best for maximizing the performance of time-critical code.
- The thumb instruction set does not include some of the instructions needed for exception handling, which automatically switches the core to ARM code for exception handling.

See the ARM7TDMI user guide for details on the core architecture, the programming model, and both the ARM and ARM thumb instruction sets.

LONG MULTIPLY (M)

The ARM7TDMI instruction set includes four extra instructions that perform 32-bit by 32-bit multiplication with a 64-bit result, and 32-bit by 32-bit multiplication-accumulation (MAC) with a 64-bit result. These results are achieved in fewer cycles than required on a standard ARM7 core.

EmbeddedICE (I)

EmbeddedICE provides integrated on-chip support for the core. The EmbeddedICE module contains the breakpoint and watchpoint registers that allow code to be halted for debugging purposes. These registers are controlled through the JTAG test port.

When a breakpoint or watchpoint is encountered, the processor halts and enters debug state. Once in a debug state, the processor registers can be inspected as well as the Flash/EE, SRAM, and memory mapped registers.

EXCEPTIONS

ARM supports five types of exceptions and a privileged processing mode for each type. The five types of exceptions are

- Normal interrupt or IRQ, which is provided to service general-purpose interrupt handling of internal and external events.
- Fast interrupt or FIQ, which is provided to service data transfers or communication channels with low latency. FIQ has priority over IRQ.
- Memory abort.
- Attempted execution of an undefined instruction.
- Software interrupt instruction (SWI), which can be used to make a call to an operating system.

Typically, the programmer defines interrupt as IRQ, but for higher priority interrupt, that is, faster response time, the programmer can define interrupt as FIQ.

ARM REGISTERS

ARM7TDMI has a total of 37 registers: 31 general-purpose registers and six status registers. Each operating mode has dedicated banked registers.

When writing user-level programs, 15 general-purpose 32-bit registers (R0 to R14), the program counter (R15), and the current program status register (CPSR) are usable. The remaining registers are used for system-level programming and exception handling only.

When an exception occurs, some of the standard registers are replaced with registers specific to the exception mode. All exception modes have replacement banked registers for the stack pointer (R13) and the link register (R14), as represented in Figure 44. The fast interrupt mode has more registers (R8 to R12) for fast interrupt processing. This means that interrupt processing can begin without the need to save or restore these registers and, thus, save critical time in the interrupt handling process.

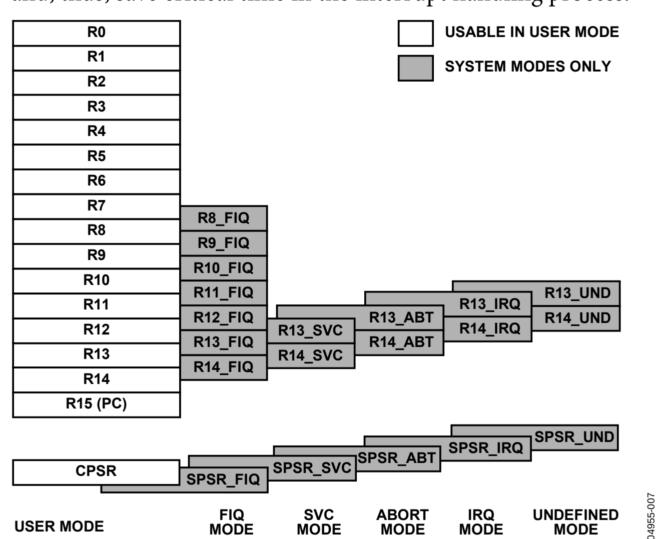


Figure 44. Register Organization

MEMORY ORGANIZATION

The ADuC7019/20/21/22/24/25/26/27/28/29 incorporate two separate blocks of memory: 8 kB of SRAM and 64 kB of on-chip Flash/EE memory. The 62 kB of on-chip Flash/EE memory is available to the user, and the remaining 2 kB are reserved for the factory-configured boot page. These two blocks are mapped as shown in Figure 45.

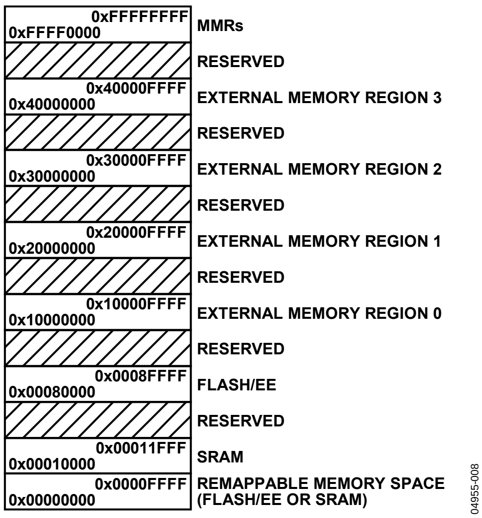


Figure 45. Physical Memory Map

Note that by default, after a reset, the Flash/EE memory is mirrored at Address 0x00000000. It is possible to remap the SRAM at Address 0x00000000 by clearing Bit 0 of the REMAP MMR. This remap function is described in more detail in the Flash/EE Memory section.

MEMORY ACCESS

The ARM7 core sees memory as a linear array of a 2^{32} byte location where the different blocks of memory are mapped as outlined in Figure 45.

The ADuC7019/20/21/22/24/25/26/27/28/29 memory organizations are configured in little endian format, which means that the least significant byte is located in the lowest byte address, and the most significant byte is in the highest byte address.

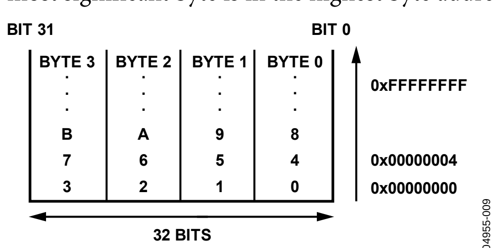


Figure 46. Little Endian Format

FLASH/EE MEMORY

The total 64 kB of Flash/EE memory is organized as 32 k × 16 bits; 31 k × 16 bits is user space and 1 k × 16 bits is reserved for the on-chip kernel. The page size of this Flash/EE memory is 512 bytes.

Sixty-two kilobytes of Flash/EE memory are available to the user as code and nonvolatile data memory. There is no distinction between data and program because ARM code shares the same space. The real width of the Flash/EE memory is 16 bits, which means that in ARM mode (32-bit instruction), two accesses to the Flash/EE are necessary for each instruction fetch. It is therefore recommended to use thumb mode when executing from Flash/EE memory for optimum access speed. The maximum access speed for the Flash/EE memory is 41.78 MHz in thumb mode and 20.89 MHz in full ARM mode. More details about Flash/EE access time are outlined in the Execution Time from SRAM and Flash/EE section.

SRAM

Eight kilobytes of SRAM are available to the user, organized as 2 k × 32 bits, that is, two words. ARM code can run directly from SRAM at 41.78 MHz, given that the SRAM array is configured as a 32-bit wide memory array. More details about SRAM access time are outlined in the Execution Time from SRAM and Flash/EE section.

MEMORY MAPPED REGISTERS

The memory mapped register (MMR) space is mapped into the upper two pages of the memory array and accessed by indirect addressing through the ARM7 banked registers.

The MMR space provides an interface between the CPU and all on-chip peripherals. All registers, except the core registers, reside in the MMR area. All shaded locations shown in Figure 47 are unoccupied or reserved locations and should not be accessed by user software. Table 16 shows the full MMR memory map.

The access time for reading from or writing to an MMR depends on the advanced microcontroller bus architecture (AMBA) bus used to access the peripheral. The processor has two AMBA buses: the advanced high performance bus (AHB) used for system modules and the advanced peripheral bus (APB) used for lower performance peripheral. Access to the AHB is one cycle, and access to the APB is two cycles. All peripherals on the ADuC7019/20/21/22/24/25/26/27/28/29 are on the APB except the Flash/EE memory, the GPIOs (see Table 78), and the PWM.

Pseudo Differential Mode

In pseudo differential mode, Channel− is linked to the V_{IN-} pin of the ADuC7019/20/21/22/24/25/26/27/28/29. SW2 switches between A (Channel−) and B (V_{REF}). The V_{IN-} pin must be connected to ground or a low voltage. The input signal on V_{IN+} can then vary from V_{IN-} to $V_{REF} + V_{IN-}$. Note that V_{IN-} must be chosen so that $V_{REF} + V_{IN-}$ does not exceed AV_{DD}.

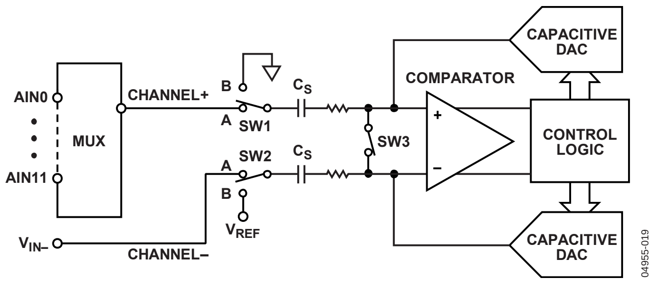


Figure 56. ADC in Pseudo Differential Mode

Single-Ended Mode

In single-ended mode, SW2 is always connected internally to ground. The V_{IN-} pin can be floating. The input signal range on V_{IN+} is 0 V to V_{REF}.

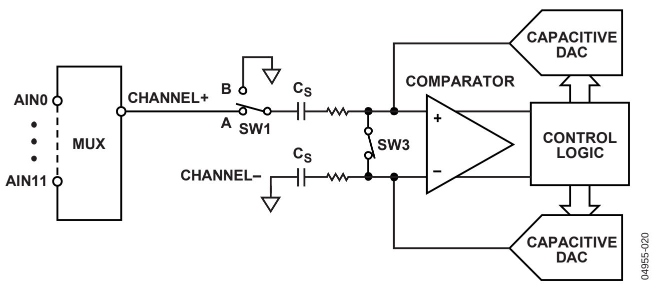


Figure 57. ADC in Single-Ended Mode

Analog Input Structure

Figure 58 shows the equivalent circuit of the analog input structure of the ADC. The four diodes provide ESD protection for the analog inputs. Care must be taken to ensure that the analog input signals never exceed the supply rails by more than 300 mV; exceeding 300 mV causes these diodes to become forward-biased and start conducting into the substrate. These diodes can conduct up to 10 mA without causing irreversible damage to the part.

The C1 capacitors in Figure 58 are typically 4 pF and can be primarily attributed to pin capacitance. The resistors are lumped components made up of the on resistance of the switches. The value of these resistors is typically about 100 Ω. The C2 capacitors are the ADC's sampling capacitors and typically have a capacitance of 16 pF.

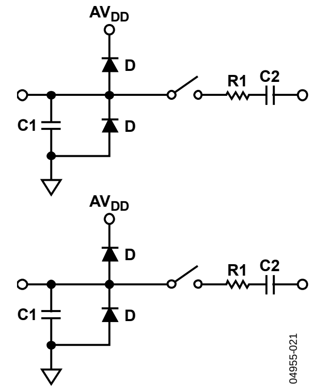


Figure 58. Equivalent Analog Input Circuit Conversion Phase: Switches Open, Track Phase: Switches Closed

For ac applications, removing high frequency components from the analog input signal is recommended by using an RC low-pass filter on the relevant analog input pins. In applications where harmonic distortion and signal-to-noise ratio are critical, the analog input should be driven from a low impedance source. Large source impedances significantly affect the ac performance of the ADC. This can necessitate the use of an input buffer amplifier. The choice of the op amp is a function of the particular application. Figure 59 and Figure 60 give an example of an ADC front end.

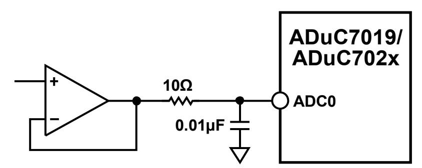


Figure 59. Buffering Single-Ended/Pseudo Differential Input

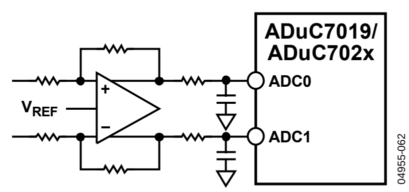


Figure 60. Buffering Differential Inputs

When no amplifier is used to drive the analog input, the source impedance should be limited to values lower than 1 kΩ. The maximum source impedance depends on the amount of total harmonic distortion (THD) that can be tolerated. The THD increases as the source impedance increases and the performance degrades.

DRIVING THE ANALOG INPUTS

Internal or external references can be used for the ADC. In the differential mode of operation, there are restrictions on the common-mode input signal (V_{CM}), which is dependent upon the reference value and supply voltage used to ensure that the signal remains within the supply rails. Table 28 gives some calculated V_{CM} minimum and V_{CM} maximum values.

DIGITAL PERIPHERALS

3-PHASE PWM

Each ADuC7019/20/21/22/24/25/26/27/28/29 provides a flexible and programmable, 3-phase pulse-width modulation (PWM) waveform generator. It can be programmed to generate the required switching patterns to drive a 3-phase voltage source inverter for ac induction motor control (ACIM). Note that only active high patterns can be produced.

The PWM generator produces three pairs of PWM signals on the six PWM output pins ($PWM0_H$, $PWM0_L$, $PWM1_H$, $PWM1_L$, $PWM2_H$, and $PWM2_L$). The six PWM output signals consist of three high-side drive signals and three low-side drive signals.

The switching frequency and dead time of the generated PWM patterns are programmable using the PWMDAT0 and PWMDAT1 MMRs. In addition, three duty-cycle control registers (PWMCH0, PWMCH1, and PWMCH2) directly control the duty cycles of the three pairs of PWM signals.

Each of the six PWM output signals can be enabled or disabled by separate output enable bits of the PWMEN register. In addition, three control bits of the PWMEN register permit crossover of the two signals of a PWM pair. In crossover mode, the PWM signal destined for the high-side switch is diverted to the complementary low-side output. The signal destined for the low-side switch is diverted to the corresponding high-side output signal.

In many applications, there is a need to provide an isolation barrier in the gate-drive circuits that turn on the inverter power devices. In general, there are two common isolation techniques: optical isolation using optocouplers and transformer isolation using pulse transformers. The PWM controller permits mixing of the output PWM signals with a high frequency chopping signal to permit easy interface to such pulse transformers. The features of this gate-drive chopping mode can be controlled by the PWMCFG register. An 8-bit value within the PWMCFG register directly controls the chopping frequency. High frequency chopping can be independently enabled for the high-side and low-side outputs using separate control bits in the PWMCFG register.

The PWM generator can operate in one of two distinct modes: single update mode or double update mode. In single update mode, the duty cycle values are programmable only once per PWM period so that the resulting PWM patterns are symmetrical about the midpoint of the PWM period. In the double update mode, a second updating of the PWM duty cycle values is implemented at the midpoint of the PWM period.

In double update mode, it is also possible to produce asymmetrical PWM patterns that produce lower harmonic distortion in 3-phase PWM inverters. This technique permits closed-loop controllers to change the average voltage applied to the machine windings at a faster rate. As a result, faster closed-loop bandwidths are achieved. The operating mode of the PWM block is selected by a control bit in the PWMCON register. In single update mode, an internal synchronization pulse, PWMSYNC, is produced at the start of each PWM period. In double update mode, an additional PWMSYNC pulse is produced at the midpoint of each PWM period.

The PWM block can also provide an internal synchronization pulse on the PWM_{SYNC} pin that is synchronized to the PWM switching frequency. In single update mode, a pulse is produced at the start of each PWM period. In double update mode, an additional pulse is produced at the mid-point of each PWM period. The width of the pulse is programmable through the PWMDAT2 register. The PWM block can also accept an external synchronization pulse on the PWM_{SYNC} pin. The selection of external synchronization or internal synchronization is in the PWMCON register. The SYNC input timing can be synchronized to the internal peripheral clock, which is selected in the PWMCON register. If the external synchronization pulse from the chip pin is asynchronous to the internal peripheral clock (typical case), the external PWMSYNC is considered asynchronous and should be synchronized. The synchronization logic adds latency and jitter from the external pulse to the actual PWM outputs. The size of the pulse on the PWM_{SYNC} pin must be greater than two core clock periods.

The PWM signals produced by the ADuC7019/20/21/22/24/25/26/27/28/29 can be shut off via a dedicated asynchronous PWM shutdown pin, PWM_{TRIP}. When brought low, PWM_{TRIP} instantaneously places all six PWM outputs in the off state (high). This hardware shutdown mechanism is asynchronous so that the associated PWM disable circuitry does not go through any clocked logic. This ensures correct PWM shutdown even in the event of a core clock loss.

Status information about the PWM system is available to the user in the PWMSTA register. In particular, the state of the PWM_{TRIP} pin is available, as well as a status bit that indicates whether operation is in the first half or the second half of the PWM period.

40-Pin Package Devices

On the 40-pin package devices, the PWM outputs are not directly accessible, as described in the General-Purpose Input/Output section. One channel can be brought out on a GPIO (see Table 78) via the PLA as shown in the following example:

```
PWMCON = 0x1;           // enables PWM o/p
PWMDAT0 = 0x055F;       // PWM switching freq

// Configure Port Pins
GP4CON = 0x300;         // P4.2 as PLA output
GP3CON = 0x1;           // P3.0 configured as
                        // output of PWM0
                        //(internally)

// PWM0 onto P4.2
PLAELM8 = 0x0035;       // P3.0 (PWM output)
                        // input of element 8
PLAELM10 = 0x0059;      // PWM from element 8
```

DESCRIPTION OF THE PWM BLOCK

A functional block diagram of the PWM controller is shown in Figure 68. The generation of the six output PWM signals on Pin $PWM0_H$ to Pin $PWM2_L$ is controlled by the following four important blocks:

- The 3-phase PWM timing unit. The core of the PWM controller, this block generates three pairs of complemented and dead-time-adjusted, center-based PWM signals. This unit also generates the internal synchronization pulse, PWMSYNC. It also controls whether the external PWM_{SYNC} pin is used.
- The output control unit. This block can redirect the outputs of the 3-phase timing unit for each channel to either the high-side or low-side output. In addition, the output control unit allows individual enabling/disabling of each of the six PWM output signals.
- The gate drive unit. This block can generate the high frequency chopping and its subsequent mixing with the PWM signals.
- The PWM shutdown controller. This block controls the PWM shutdown via the PWM_{TRIP} pin and generates the correct reset signal for the timing unit.

The PWM controller is driven by the ADuC7019/20/21/22/24/25/26/27/28/29 core clock frequency and is capable of generating two interrupts to the ARM core. One interrupt is generated on the occurrence of a PWMSYNC pulse, and the other is generated on the occurrence of any PWM shutdown action.

3-Phase Timing Unit

PWM Switching Frequency (PWMDAT0 MMR)

The PWM switching frequency is controlled by the PWM period register, PWMDAT0. The fundamental timing unit of the PWM controller is

$$t_{CORE} = 1/f_{CORE}$$

where f_{CORE} is the core frequency of the MicroConverter.

Therefore, for a 41.78 MHz f_{CORE}, the fundamental time increment is 24 ns. The value written to the PWMDAT0 register is effectively the number of f_{CORE} clock increments in one-half a PWM period. The required PWMDAT0 value is a function of the desired PWM switching frequency (f_{PWN}) and is given by

$$PWMDAT0 = f_{CORE}/(2 \times f_{PWM})$$

Therefore, the PWM switching period, t_S, can be written as

$$t_S = 2 \times PWMDAT0 \times t_{CORE}$$

The largest value that can be written to the 16-bit PWMDAT0 MMR is 0xFFFF = 65,535, which corresponds to a minimum PWM switching frequency of

$$f_{PWM(min)} = 41.78 \times 10^6/(2 \times 65{,}535) = 318.75 \text{ Hz}$$

Note that PWMDAT0 values of 0 and 1 are not defined and should not be used.

PWM Switching Dead Time (PWMDAT1 MMR)

The second important parameter that must be set up in the initial configuration of the PWM block is the switching dead time. This is a short delay time introduced between turning off one PWM signal (0H, for example) and turning on the complementary signal (0L). This short time delay is introduced to permit the power switch to be turned off (in this case, 0H) to completely recover its blocking capability before the complementary switch is turned on. This time delay prevents a potentially destructive short-circuit condition from developing across the dc link capacitor of a typical voltage source inverter.

The dead time is controlled by the 10-bit, read/write PWMDAT1 register. There is only one dead-time register that controls the dead time inserted into all three pairs of PWM output signals. The dead time, t_D, is related to the value in the PWMDAT1 register by

$$t_D = PWMDAT1 \times 2 \times t_{CORE}$$

Therefore, a PWMDAT1 value of 0x00A (= 10), introduces a 426 ns delay between the turn-off on any PWM signal (0H, for example) and the turn-on of its complementary signal (0L). The amount of the dead time can, therefore, be programmed in increments of $2t_{CORE}$ (or 49 ns for a 41.78 MHz core clock).

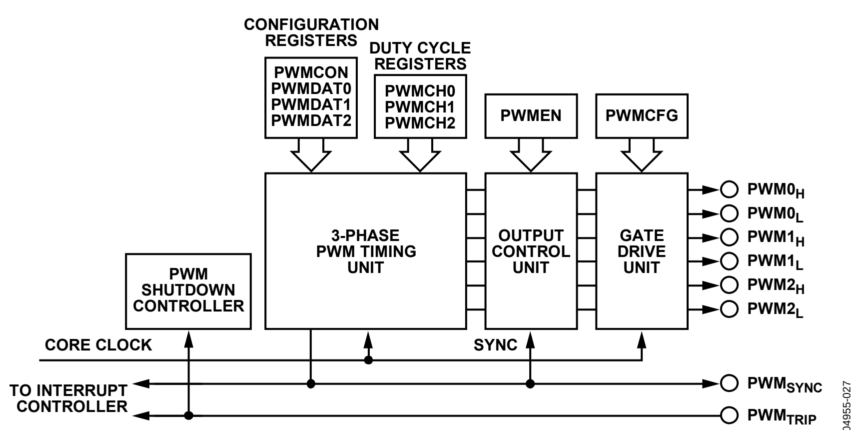


Figure 68. Overview of the PWM Controller

Both switching edges are moved by an equal amount ($PWMDAT1 \times t_{CORE}$) to preserve the symmetrical output patterns.

Also shown are the PWMSYNC pulse and Bit 0 of the PWMSTA register, which indicates whether operation is in the first or second half cycle of the PWM period.

The resulting on times of the PWM signals over the full PWM period (two half periods) produced by the timing unit can be written as follows:

On the high side

$$t_{0HH} = PWMDAT0 + 2(PWMCH0 - PWMDAT1) \times t_{CORE}$$

$$t_{0HL} = PWMDAT0 - 2(PWMCH0 - PWMDAT1) \times t_{CORE}$$

and the corresponding duty cycles (d)

$$d_{0H} = t_{0HH}/t_S = ½ + (PWMCH0 - PWMDAT1)/PWMDAT0$$

and on the low side

$$t_{0LH} = PWMDAT0 - 2(PWMCH0 + PWMDAT1) \times t_{CORE}$$

$$t_{0LL} = PWMDAT0 + 2(PWMCH0 + PWMDAT1) \times t_{CORE}$$

and the corresponding duty cycles (d)

$$d_{0L} = t_{0LH}/t_S = ½ - (PWMCH0 + PWMDAT1)/PWMDAT0$$

The minimum permissible t_{0H} and t_{0L} values are zero, corresponding to a 0% duty cycle. In a similar fashion, the maximum value is t_S, corresponding to a 100% duty cycle.

Figure 70 shows the output signals from the timing unit for operation in double update mode. It illustrates a general case where the switching frequency, dead time, and duty cycle are all changed in the second half of the PWM period. The same value for any or all of these quantities can be used in both halves of the PWM cycle. However, there is no guarantee that symmetrical PWM signals are produced by the timing unit in double update mode. Figure 70 also shows that the dead time insertions into the PWM signals are done in the same way as in single update mode.

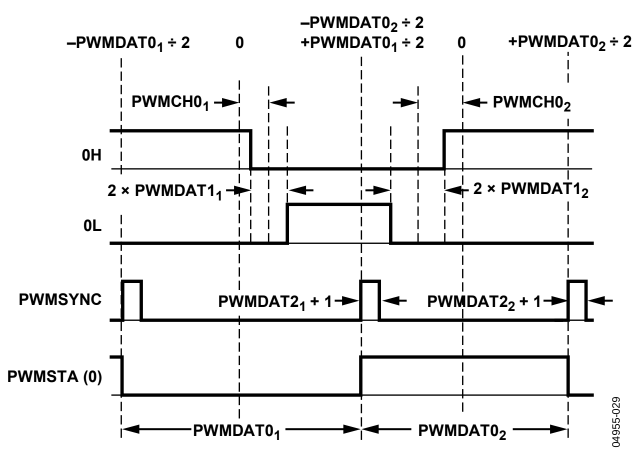


Figure 70. Typical PWM Outputs of the 3-Phase Timing Unit (Double Update Mode)

In general, the on times of the PWM signals in double update mode can be defined as follows:

On the high side

$$t_{0HH} = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2) \times t_{CORE}$$

$$t_{0HL} = (PWMDAT0_1/2 + PWMDAT0_2/2 - PWMCH0_1 - PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2) \times t_{CORE}$$

where Subscript *1* refers to the value of that register during the first half cycle, and Subscript *2* refers to the value during the second half cycle.

The corresponding duty cycles (d) are

$$d_{0H} = t_{0HH}/t_S = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2)/(PWMDAT0_1 + PWMDAT0_2)$$

On the low side

$$t_{0LH} = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2) \times t_{CORE}$$

$$t_{0LL} = (PWMDAT0_1/2 + PWMDAT0_2/2 - PWMCH0_1 - PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2) \times t_{CORE}$$

where Subscript *1* refers to the value of that register during the first half cycle, and Subscript *2* refers to the value during the second half cycle.

The corresponding duty cycles (d) are

$$d_{0L} = t_{0LH}/t_S = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2)/(PWMDAT0_1 + PWMDAT0_2)$$

For the completely general case in double update mode (see Figure 70), the switching period is given by

$$t_S = (PWMDAT0_1 + PWMDAT0_2) \times t_{CORE}$$

Again, the values of t_{0H} and t_{0L} are constrained to lie between zero and t_S.

PWM signals similar to those illustrated in Figure 69 and Figure 70 can be produced on the 1H, 1L, 2H, and 2L outputs by programming the PWMCH1 and PWMCH2 registers in a manner identical to that described for PWMCH0. The PWM controller does not produce any PWM outputs until all of the PWMDAT0, PWMCH0, PWMCH1, and PWMCH2 registers have been written to at least once. When these registers are written, internal counting of the timers in the 3-phase timing unit is enabled.

Writing to the PWMDAT0 register starts the internal timing of the main PWM timer. Provided that the PWMDAT0 register is written to prior to the PWMCH0, PWMCH1, and PWMCH2 registers in the initialization, the first PWMSYNC pulse and interrupt (if enabled) appear $1.5 \times t_{CORE} \times PWMDAT0$ seconds after the initial write to the PWMDAT0 register in single update mode. In double update mode, the first PWMSYNC pulse appears after $PWMDAT0 \times t_{CORE}$ seconds.

The serial communication adopts an asynchronous protocol, which supports various word lengths, stop bits, and parity generation options selectable in the configuration register.

Baud Rate Generation

There are two ways of generating the UART baud rate, normal 450 UART baud rate generation and the fractional divider.

Normal 450 UART Baud Rate Generation

The baud rate is a divided version of the core clock using the values in the COMDIV0 and COMDIV1 MMRs (16-bit value, DL).

$$\text{Baud Rate} = \frac{41.78\,\text{MHz}}{2^{CD} - 16 \times 2 \times DL}$$

Table 93 gives some common baud rate values.

Table 93. Baud Rate Using the Normal Baud Rate Generator

Baud Rate	CD	DL	Actual Baud Rate	% Error
9600	0	0x88	9600	0
19,200	0	0x44	19,200	0
115,200	0	0x0B	118,691	3
9600	3	0x11	9600	0
19,200	3	0x08	20,400	6.25
115,200	3	0x01	163,200	41.67

Fractional Divider

The fractional divider, combined with the normal baud rate generator, produces a wider range of more accurate baud rates.

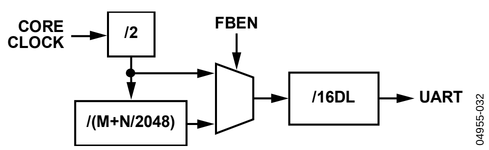


Figure 75. Baud Rate Generation Options

Calculation of the baud rate using fractional divider is as follows:

$$Baud\ \ Rate = \frac{41.78\,\text{MHz}}{2^{CD} \times 16 \times DL \times 2 \times \left(M + \frac{N}{2048}\right)}$$

$$M + \frac{N}{2048} = \frac{41.78\,\text{MHz}}{\text{Baud Rate} \times 2^{CD} \times 16 \times DL \times 2}$$

For example, generation of 19,200 baud with CD bits = 3 (Table 93 gives DL = 0x08) is

$$M + \frac{N}{2048} = \frac{41.78\,\text{MHz}}{19200 \times 2^{3} \times 16 \times 8 \times 2}$$

$$M + \frac{N}{2048} = 1.06$$

where:
$M = 1$
$N = 0.06 \times 2048 = 128$

$$\text{Baud Rate} = \frac{41.78\,\text{MHz}}{2^{3} \times 16 \times 8 \times 2 \times \frac{128}{2048}}$$

where:
Baud Rate = 19,200 bps

Error = 0%, compared to 6.25% with the normal baud rate generator.

UART Register Definitions

The UART interface consists of 12 registers: COMTX, COMRX, COMDIV0, COMIEN0, COMDIV1, COMIID0, COMCON0, COMCON1, COMSTA0, COMSTA1, COMSCR, and COMDIV2.

Table 94. COMTX Register

Name	Address	Default Value	Access
COMTX	0xFFFF0700	0x00	R/W

COMTX is an 8-bit transmit register.

Table 95. COMRX Register

Name	Address	Default Value	Access
COMRX	0xFFFF0700	0x00	R

COMRX is an 8-bit receive register.

Table 96. COMDIV0 Register

Name	Address	Default Value	Access
COMDIV0	0xFFFF0700	0x00	R/W

COMDIV0 is a low byte divisor latch. COMTX, COMRX, and COMDIV0 share the same address location. COMTX and COMRX can be accessed when Bit 7 in the COMCON0 register is cleared. COMDIV0 can be accessed when Bit 7 of COMCON0 is set.

Table 97. COMIEN0 Register

Name	Address	Default Value	Access
COMIEN0	0xFFFF0704	0x00	R/W

COMIEN0 is the interrupt enable register.

Table 98. COMIEN0 MMR Bit Descriptions

Bit	Name	Description
7:4	N/A	Reserved.
3	EDSSI	Modem status interrupt enable bit. Set by user to enable generation of an interrupt if any of COMSTA1[3:1] is set. Cleared by user.
2	ELSI	Rx status interrupt enable bit. Set by user to enable generation of an interrupt if any of COMSTA0[4:1] is set. Cleared by user.
1	ETBEI	Enable transmit buffer empty interrupt. Set by user to enable interrupt when buffer is empty during a transmission. Cleared by user.
0	ERBFI	Enable receive buffer full interrupt. Set by user to enable interrupt when buffer is full during a reception. Cleared by user.

Table 116. COMIID1 MMR Bit Descriptions

Bit 3:1 Status Bits	Bit 0 NINT	Priority	Definition	Clearing Operation
000	1		No interrupt	
110	0	2	Matching network address	Read COMRX
101	0	3	Address transmitted, buffer empty	Write data to COMTX or read COMIID0
011	0	1	Receive line status interrupt	Read COMSTA0
010	0	2	Receive buffer full interrupt	Read COMRX
001	0	3	Transmit buffer empty interrupt	Write data to COMTX or read COMIID0
000	0	4	Modem status interrupt	Read COMSTA1

Note that to receive a network address interrupt, the slave must ensure that Bit 0 of COMIEN0 (enable receive buffer full interrupt) is set to 1.

Table 117. COMADR Register

Name	Address	Default Value	Access
COMADR	0xFFFF0728	0xAA	R/W

COMADR is an 8-bit, read/write network address register that holds the address checked for by the network addressable UART. Upon receiving this address, the device interrupts the processor and/or sets the appropriate status bit in COMIID1.

SERIAL PERIPHERAL INTERFACE

The ADuC7019/20/21/22/24/25/26/27/28/29 integrate a complete hardware serial peripheral interface (SPI) on-chip. SPI is an industry standard, synchronous serial interface that allows eight bits of data to be synchronously transmitted and simultaneously received, that is, full duplex up to a maximum bit rate of 3.48 Mb, as shown in Table 118. The SPI interface is not operational with core clock divider (CD) bits. POWCON[2:0] = 6 or 7 in master mode.

The SPI port can be configured for master or slave operation. and typically consists of four pins: MISO (P1.5), MOSI (P1.6), SCLK (P1.4), and $\overline{\text{CS}}$ (P1.7).

On the transmit side, the SPITX register (and a TX shift register outside it) loads data onto the transmit pin (in slave mode, MISO; in master mode, MOSI). The transmit status bit, Bit 0, in SPISTA indicates whether there is valid data in the SPITX register.

Similarly, the receive data path consists of the SPIRX register (and an RX shift register). SPISTA, Bit 3 indicates whether there is valid data in the SPIRX register. If valid data in the SPIRX register is overwritten or if valid data in the RX shift register is discarded, SPISTA, Bit 5 (the overflow bit) is set.

MISO (Master In, Slave Out) Pin

The MISO pin is configured as an input line in master mode and an output line in slave mode. The MISO line on the master (data in) should be connected to the MISO line in the slave device (data out). The data is transferred as byte wide (8-bit) serial data, MSB first.

MOSI (Master Out, Slave In) Pin

The MOSI pin is configured as an output line in master mode and an input line in slave mode. The MOSI line on the master (data out) should be connected to the MOSI line in the slave device (data in). The data is transferred as byte wide (8-bit) serial data, MSB first.

SCLK (Serial Clock I/O) Pin

The master serial clock (SCLK) is used to synchronize the data being transmitted and received through the MOSI SCLK period. Therefore, a byte is transmitted/received after eight SCLK periods. The SCLK pin is configured as an output in master mode and as an input in slave mode.

In master mode, the polarity and phase of the clock are controlled by the SPICON register, and the bit rate is defined in the SPIDIV register as follows:

$$f_{SERIAL\ CLOCK} = \frac{f_{UCLK}}{2 \times (1 + SPIDIV)}$$

The maximum speed of the SPI clock is dependent on the clock divider bits and is summarized in Table 118.

Table 118. SPI Speed vs. Clock Divider Bits in Master Mode

CD Bits	0	1	2	3	4	5
SPIDIV in Hex	0x05	0x0B	0x17	0x2F	0x5F	0xBF
SPI dpeed in MHz	3.482	1.741	0.870	0.435	0.218	0.109

In slave mode, the SPICON register must be configured with the phase and polarity of the expected input clock. The slave accepts data from an external master up to 10.4 Mb at CD = 0. The formula to determine the maximum speed is as follows:

$$f_{SERIAL\ CLOCK} = \frac{f_{HCLK}}{4}$$

In both master and slave modes, data is transmitted on one edge of the SCL signal and sampled on the other. Therefore, it is important that the polarity and phase be configured the same for the master and slave devices.

Chip Select ($\overline{\text{CS}}$ Input) Pin

In SPI slave mode, a transfer is initiated by the assertion of $\overline{\text{CS}}$, which is an active low input signal. The SPI port then transmits and receives 8-bit data until the transfer is concluded by deassertion of $\overline{\text{CS}}$. In slave mode, $\overline{\text{CS}}$ is always an input.

I²C-COMPATIBLE INTERFACES

The ADuC7019/20/21/22/24/25/26/27/28/29 support two licensed I²C interfaces. The I²C interfaces are both implemented as a hard-ware master and a full slave interface. Because the two I²C inter-faces are identical, this data sheet describes only I2C0 in detail. Note that the two masters and one of the slaves have individual interrupts (see the Interrupt System section).

Note that when configured as an I²C master device, the ADuC7019/20/21/22/24/25/26/27/28/29 cannot generate a repeated start condition.

The two GPIO pins used for data transfer, SDAx and SCLx, are configured in a wired-AND format that allows arbitration in a multimaster system. These pins require external pull-up resistors. Typical pull-up values are 10 kΩ.

The I²C bus peripheral address in the I²C bus system is pro-grammed by the user. This ID can be modified any time a transfer is not in progress. The user can configure the interface to respond to four slave addresses.

The transfer sequence of an I²C system consists of a master device initiating a transfer by generating a start condition while the bus is idle. The master transmits the slave device address and the direction of the data transfer during the initial address transfer. If the master does not lose arbitration and the slave acknowledges, the data transfer is initiated. This continues until the master issues a stop condition and the bus becomes idle.

The I²C peripheral can be configured only as a master or slave at any given time. The same I²C channel cannot simultaneously support master and slave modes.

Serial Clock Generation

The I²C master in the system generates the serial clock for a transfer. The master channel can be configured to operate in fast mode (400 kHz) or standard mode (100 kHz).

The bit rate is defined in the I2C0DIV MMR as follows:

$$f_{SERIAL\ CLOCK} = \frac{f_{UCLK}}{(2 + DIVH) + (2 + DIVL)}$$

where:
f_{UCLK} = clock before the clock divider.
$DIVH$ = the high period of the clock.
$DIVL$ = the low period of the clock.

Thus, for 100 kHz operation,

$$DIVH = DIVL = 0xCF$$

and for 400 kHz,

$$DIVH = 0x28,\ DIVL = 0x3C$$

The I2CxDIV registers correspond to DIVH:DIVL.

Slave Addresses

The registers I2C0ID0, I2C0ID1, I2C0ID2, and I2C0ID3 contain the device IDs. The device compares the four I2C0IDx registers to the address byte. To be correctly addressed, the seven MSBs of either ID register must be identical to that of the seven MSBs of the first received address byte. The LSB of the ID registers (the transfer direction bit) is ignored in the process of address recognition.

I²C Registers

The I²C peripheral interface consists of 18 MMRs, which are discussed in this section.

Table 126. I2CxMSTA Registers

Name	Address	Default Value	Access
I2C0MSTA	0xFFFF0800	0x00	R/W
I2C1MSTA	0xFFFF0900	0x00	R/W

I2CxMSTA are status registers for the master channel.

Table 127. I2C0MSTA MMR Bit Descriptions

Bit	Access Type	Description
7	R/W	Master transmit FIFO flush. Set by user to flush the master Tx FIFO. Cleared automatically after the master Tx FIFO is flushed. This bit also flushes the slave receive FIFO.
6	R	Master busy. Set automatically if the master is busy. Cleared automatically.
5	R	Arbitration loss. Set in multimaster mode if another master has the bus. Cleared when the bus becomes available.
4	R	No ACK. Set automatically if there is no acknowledge of the address by the slave device. Cleared automatically by reading the I2C0MSTA register.
3	R	Master receive IRQ. Set after receiving data. Cleared automatically by reading the I2C0MRX register.
2	R	Master transmit IRQ. Set at the end of a transmission. Cleared automatically by writing to the I2C0MTX register.
1	R	Master transmit FIFO underflow. Set automatically if the master transmit FIFO is underflowing. Cleared automatically by writing to the I2C0MTX register.
0	R	Master TX FIFO not full. Set automatically if the slave transmit FIFO is not full. Cleared automatically by writing twice to the I2C0STX register.

Table 128. I2CxSSTA Registers

Name	Address	Default Value	Access
I2C0SSTA	0xFFFF0804	0x01	R
I2C1SSTA	0xFFFF0904	0x01	R

I2CxSSTA are status registers for the slave channel.

Table 153. PLAADC Register

Name	Address	Default Value	Access
PLAADC	0xFFFF0B48	0x00000000	R/W

PLAADC is the PLA source for the ADC start conversion signal.

Table 154. PLAADC MMR Bit Descriptions

Bit	Value	Description
31:5		Reserved.
4		ADC start conversion enable bit. Set by user to enable ADC start conversion from PLA. Cleared by user to disable ADC start conversion from PLA.
3:0		ADC start conversion source.
	0000	PLA Element 0.
	0001	PLA Element 1.
	1111	PLA Element 15.

Table 155. PLADIN Register

Name	Address	Default Value	Access
PLADIN	0xFFFF0B4C	0x00000000	R/W

PLADIN is a data input MMR for PLA.

Table 156. PLADIN MMR Bit Descriptions

Bit	Description
31:16	Reserved.
15:0	Input bit to Element 15 to Element 0.

Table 157. PLADOUT Register

Name	Address	Default Value	Access
PLADOUT	0xFFFF0B50	0x00000000	R

PLADOUT is a data output MMR for PLA. This register is always updated.

Table 158. PLADOUT MMR Bit Descriptions

Bit	Description
31:16	Reserved.
15:0	Output bit from Element 15 to Element 0.

Table 159. PLALCK Register

Name	Address	Default Value	Access
PLALCK	0xFFFF0B54	0x00	W

PLALCK is a PLA lock option. Bit 0 is written only once. When set, it does not allow modifying any of the PLA MMRs, except PLADIN. A PLA tool is provided in the development system to easily configure the PLA.

Timer1 (General-Purpose Timer)

Timer1 is a general-purpose, 32-bit timer (count down or count up) with a programmable prescaler. The source can be the 32 kHz external crystal, the core clock frequency, or an external GPIO (P1.0 or P0.6). The maximum frequency of the clock input is 44 Mhz). This source can be scaled by a factor of 1, 16, 256, or 32,768.

The counter can be formatted as a standard 32-bit value or as hours: minutes: seconds: hundredths.

Timer1 has a capture register (T1CAP) that can be triggered by a selected IRQ source initial assertion. This feature can be used to determine the assertion of an event more accurately than the precision allowed by the RTOS timer when the IRQ is serviced.

Timer1 can be used to start ADC conversions as shown in the block diagram in Figure 78.

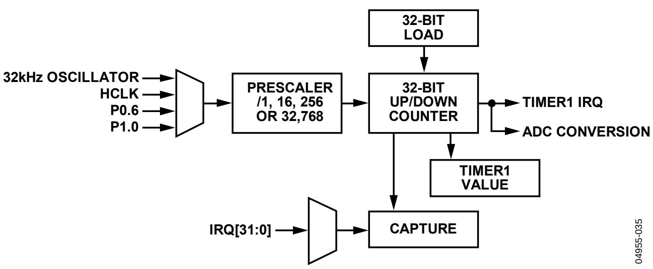


Figure 78. Timer1 Block Diagram

The Timer1 interface consists of five MMRs: T1LD, T1VAL, T1CON, T1CLRI, and T1CAP.

Table 177. T1LD Register

Name	Address	Default Value	Access
T1LD	0xFFFF0320	0x00000000	R/W

T1LD is a 32-bit load register.

Table 178. T1VAL Register

Name	Address	Default Value	Access
T1VAL	0xFFFF0324	0xFFFFFFFF	R

T1VAL is a 32-bit read-only register that represents the current state of the counter.

Table 179. T1CON Register

Name	Address	Default Value	Access
T1CON	0xFFFF0328	0x0000	R/W

T1CON is the configuration MMR described in Table 180.

Table 180. T1CON MMR Bit Descriptions

Bit	Value	Description
31:18		Reserved.
17		Event select bit. Set by user to enable time capture of an event. Cleared by user to disable time capture of an event.
16:12		Event select range, 0 to 31. These events are as described in Table 160. All events are offset by two; that is, Event 2 in Table 160 becomes Event 0 for the purposes of Timer1.
11:9		Clock select.
	000	Core clock (HCLK).
	001	External 32.768 kHz crystal.
	010	P1.0 rising edge triggered.
	011	P0.6 rising edge triggered.
8		Count up. Set by user for Timer1 to count up. Cleared by user for Timer1 to count down by default.
7		Timer1 enable bit. Set by user to enable Timer1. Cleared by user to disable Timer1 by default.
6		Timer1 mode. Set by user to operate in periodic mode. Cleared by user to operate in free-running mode. Default mode.
5:4		Format.
	00	Binary.
	01	Reserved.
	10	Hr: min: sec: hundredths (23 hours to 0 hour).
	11	Hr: min: sec: hundredths (255 hours to 0 hour).
3:0		Prescale.
	0000	Source Clock/1.
	0100	Source Clock/16.
	1000	Source Clock/256.
	1111	Source Clock/32,768.

Table 181. T1CLRI Register

Name	Address	Default Value	Access
T1CLRI	0xFFFF032C	0xFF	W

T1CLRI is an 8-bit register. Writing any value to this register clears the Timer1 interrupt.

Table 182. T1CAP Register

Name	Address	Default Value	Access
T1CAP	0xFFFF0330	0x00000000	R/W

T1CAP is a 32-bit register. It holds the value contained in T1VAL when a particular event occurs. This event must be selected in T1CON.

Timer2 (Wake-Up Timer)

Timer2 is a 32-bit wake-up timer (count down or count up) with a programmable prescaler. The source can be the 32 kHz external crystal, the core clock frequency, or the internal 32 kHz oscillator. The clock source can be scaled by a factor of 1, 16, 256, or 32,768. The wake-up timer continues to run when the core clock is disabled.

The counter can be formatted as plain 32-bit value or as hours: minutes: seconds: hundredths.

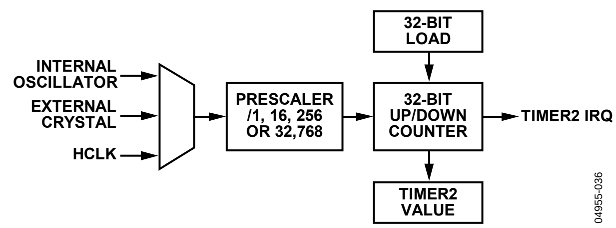


Figure 79. Timer2 Block Diagram

The Timer2 interface consists of four MMRs: T2LD, T2VAL, T2CON, and T2CLRI.

Table 183. T2LD Register

Name	Address	Default Value	Access
T2LD	0xFFFF0340	0x00000000	R/W

T2LD is a 32-bit register load register.

Table 184. T2VAL Register

Name	Address	Default Value	Access
T2VAL	0xFFFF0344	0xFFFFFFFF	R

T2VAL is a 32-bit read-only register that represents the current state of the counter.

Table 185. T2CON Register

Name	Address	Default Value	Access
T2CON	0xFFFF0348	0x0000	R/W

T2CON is the configuration MMR described in Table 186.